

# MC14027B

## Dual J-K Flip-Flop

The MC14027B dual J-K flip-flop has independent J, K, Clock (C), Set (S) and Reset (R) inputs for each flip-flop. These devices may be used in control, register, or toggle functions.

- Diode Protection on All Inputs
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Logic Swing Independent of Fanout
- Logic Edge-Clocked Flip-Flop Design —  
Logic state is retained indefinitely with clock level either high or low; information is transferred to the output only on the positive-going edge of the clock pulse
- Capable of Driving Two Low-power TTL Loads or One Low-power Schottky TTL Load Over the Rated Temperature Range
- Pin-for-Pin Replacement for CD4027B

### MAXIMUM RATINGS (Voltages Referenced to V<sub>SS</sub>) (Note 2.)

Symbol	Parameter	Value	Unit
V <sub>DD</sub>	DC Supply Voltage Range	-0.5 to +18.0	V
V <sub>in</sub> , V <sub>out</sub>	Input or Output Voltage Range (DC or Transient)	-0.5 to V <sub>DD</sub> + 0.5	V
I <sub>in</sub> , I <sub>out</sub>	Input or Output Current (DC or Transient) per Pin	±10	mA
P <sub>D</sub>	Power Dissipation, per Package (Note 3.)	500	mW
T <sub>A</sub>	Ambient Temperature Range	-55 to +125	°C
T <sub>stg</sub>	Storage Temperature Range	-65 to +150	°C
T <sub>L</sub>	Lead Temperature (8-Second Soldering)	260	°C

2. Maximum Ratings are those values beyond which damage to the device may occur.
3. Temperature Derating:  
Plastic "P and D/DW" Packages: - 7.0 mW/°C From 65°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V<sub>in</sub> and V<sub>out</sub> should be constrained to the range V<sub>SS</sub> ≤ (V<sub>in</sub> or V<sub>out</sub>) ≤ V<sub>DD</sub>.

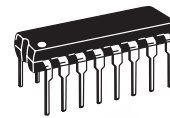
Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V<sub>SS</sub> or V<sub>DD</sub>). Unused outputs must be left open.



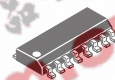
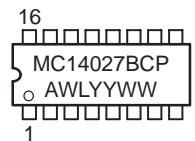
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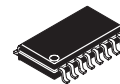
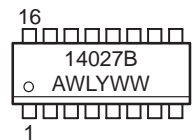
### MARKING DIAGRAMS



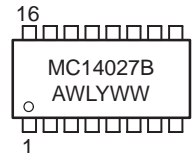
**PDIP-16  
P SUFFIX  
CASE 648**



**SOIC-16  
D SUFFIX  
CASE 751B**



**SOEIAJ-16  
F SUFFIX  
CASE 966**



A = Assembly Location  
WL or L = Wafer Lot  
YY or Y = Year  
WW or W = Work Week

### ORDERING INFORMATION

Device	Package	Shipping
MC14027BCP	PDIP-16	2000/Box
MC14027BD	SOIC-16	2400/Box
MC14027BDR2	SOIC-16	2500/Tape & Reel
MC14027BF	SOEIAJ-16	See Note 1.
MC14027BFEL	SOEIAJ-16	See Note 1.

1. For ordering information on the EIAJ version of the SOIC packages, please contact your local ON Semiconductor representative.

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## TRUTH TABLE

Inputs						Outputs*	
C†	J	K	S	R	Q <sub>n</sub> ‡	Q <sub>n+1</sub>	Q <sub>n+1</sub>
↗	1	X	0	0	0	1	0
↗	X	0	0	0	1	1	0
↗	0	X	0	0	0	0	1
↗	X	1	0	0	1	0	1
↗	1	1	0	0	Q <sub>0</sub>	Q <sub>0</sub>	Q <sub>0</sub>
↘	X	X	0	0	X	Q <sub>n</sub>	Q <sub>n</sub>
X	X	X	1	0	X	1	0
X	X	X	0	1	X	0	1
X	X	X	1	1	X	1	1

No Change

X = Don't Care

† = Level Change

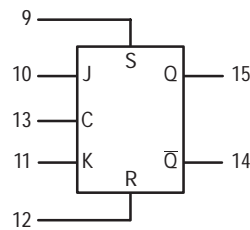
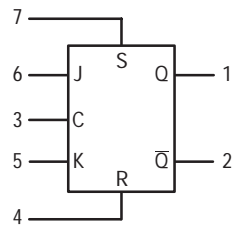
‡ = Present State

\* = Next State

## PIN ASSIGNMENT

Q <sub>A</sub>	1	16	V <sub>DD</sub>
Q̄ <sub>A</sub>	2	15	Q <sub>B</sub>
C <sub>A</sub>	3	14	Q̄ <sub>B</sub>
R <sub>A</sub>	4	13	C <sub>B</sub>
K <sub>A</sub>	5	12	R <sub>B</sub>
J <sub>A</sub>	6	11	K <sub>B</sub>
S <sub>A</sub>	7	10	J <sub>B</sub>
V <sub>SS</sub>	8	9	S <sub>B</sub>

## BLOCK DIAGRAM



V<sub>DD</sub> = PIN 16

V<sub>SS</sub> = PIN 8

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## ELECTRICAL CHARACTERISTICS (Voltages Referenced to $V_{SS}$ )

Characteristic	Symbol	$V_{DD}$ Vdc	-55°C		25°C			125°C		Unit
			Min	Max	Min	Typ (4.)	Max	Min	Max	
Output Voltage $V_{in} = V_{DD}$ or 0  $V_{in} = 0$ or $V_{DD}$	"0" Level $V_{OL}$	5.0	—	0.05	—	0	0.05	—	0.05	Vdc
		10	—	0.05	—	0	0.05	—	0.05	
		15	—	0.05	—	0	0.05	—	0.05	
	"1" Level $V_{OH}$	5.0	4.95	—	4.95	5.0	—	4.95	—	Vdc
		10	9.95	—	9.95	10	—	9.95	—	
		15	14.95	—	14.95	15	—	14.95	—	
Input Voltage $(V_O = 4.5$ or $0.5$ Vdc) $(V_O = 9.0$ or $1.0$ Vdc) $(V_O = 13.5$ or $1.5$ Vdc)  $(V_O = 0.5$ or $4.5$ Vdc) $(V_O = 1.0$ or $9.0$ Vdc) $(V_O = 1.5$ or $13.5$ Vdc)	"0" Level $V_{IL}$	5.0	—	1.5	—	2.25	1.5	—	1.5	Vdc
		10	—	3.0	—	4.50	3.0	—	3.0	
		15	—	4.0	—	6.75	4.0	—	4.0	
	"1" Level $V_{IH}$	5.0	3.5	—	3.5	2.75	—	3.5	—	Vdc
		10	7.0	—	7.0	5.50	—	7.0	—	
		15	11	—	11	8.25	—	11	—	
Output Drive Current $(V_{OH} = 2.5$ Vdc) $(V_{OH} = 4.6$ Vdc) $(V_{OH} = 9.5$ Vdc) $(V_{OH} = 13.5$ Vdc)  $(V_{OL} = 0.4$ Vdc) $(V_{OL} = 0.5$ Vdc) $(V_{OL} = 1.5$ Vdc)	Source $I_{OH}$	5.0	-3.0	—	-2.4	-4.2	—	-1.7	—	mAdc
		5.0	-0.64	—	-0.51	-0.88	—	-0.36	—	
		10	-1.6	—	-1.3	-2.25	—	-0.9	—	
		15	-4.2	—	-3.4	-8.8	—	-2.4	—	
	Sink $I_{OL}$	5.0	0.64	—	0.51	0.88	—	0.36	—	mAdc
		10	1.6	—	1.3	2.25	—	0.9	—	
15		4.2	—	3.4	8.8	—	2.4	—		
Input Current	$I_{in}$	15	—	$\pm 0.1$	—	$\pm 0.00001$	$\pm 0.1$	—	$\pm 1.0$	$\mu$ Adc
Input Capacitance $(V_{in} = 0)$	$C_{in}$	—	—	—	—	5.0	7.5	—	—	pF
Quiescent Current (Per Package)	$I_{DD}$	5.0	—	1.0	—	0.002	1.0	—	30	$\mu$ Adc
		10	—	2.0	—	0.004	2.0	—	60	
		15	—	4.0	—	0.006	4.0	—	120	
Total Supply Current <sup>(5.)</sup> <sup>(6.)</sup> (Dynamic plus Quiescent, Per Package) $(C_L = 50$ pF on all outputs, all buffers switching)	$I_T$	5.0	$I_T = (0.8 \mu\text{A/kHz}) f + I_{DD}$							$\mu$ Adc
		10	$I_T = (1.6 \mu\text{A/kHz}) f + I_{DD}$							
		15	$I_T = (2.4 \mu\text{A/kHz}) f + I_{DD}$							

4. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

5. The formulas given are for the typical characteristics only at 25°C.

6. To calculate total supply current at loads other than 50 pF:

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) Vfk$$

where:  $I_T$  is in  $\mu\text{A}$  (per package),  $C_L$  in pF,  $V = (V_{DD} - V_{SS})$  in volts,  $f$  in kHz is input frequency, and  $k = 0.002$ .

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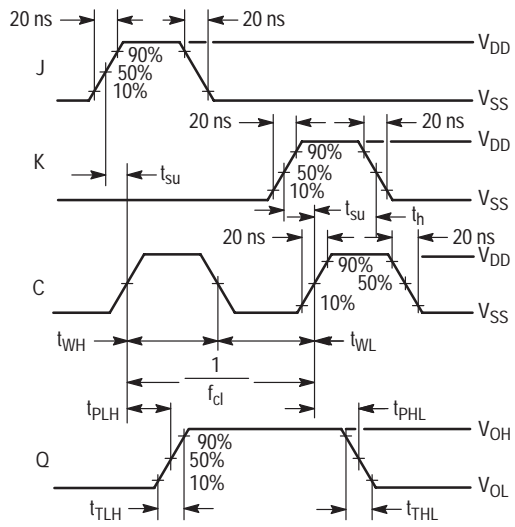
### SWITCHING CHARACTERISTICS (7.) ( $C_L = 50 \text{ pF}$ , $T_A = 25^\circ\text{C}$ )

Characteristic	Symbol	$V_{DD}$	Min	Typ (8.)	Max	Unit
Output Rise and Fall Time $t_{TLH}, t_{THL} = (1.5 \text{ ns/pF}) C_L + 25 \text{ ns}$ $t_{TLH}, t_{THL} = (0.75 \text{ ns/pF}) C_L + 12.5 \text{ ns}$ $t_{TLH}, t_{THL} = (0.55 \text{ ns/pF}) C_L + 12.5 \text{ ns}$	$t_{TLH},$ $t_{THL}$	5.0 10 15	— — —	100 50 40	200 100 80	ns
Propagation Delay Times** Clock to Q, Q $t_{PLH}, t_{PHL} = (1.7 \text{ ns/pF}) C_L + 90 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.66 \text{ ns/pF}) C_L + 42 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.5 \text{ ns/pF}) C_L + 25 \text{ ns}$ Set to Q, Q $t_{PLH}, t_{PHL} = (1.7 \text{ ns/pF}) C_L + 90 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.66 \text{ ns/pF}) C_L + 42 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.5 \text{ ns/pF}) C_L + 25 \text{ ns}$ Reset to Q, Q $t_{PLH}, t_{PHL} = (1.7 \text{ ns/pF}) C_L + 265 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.66 \text{ ns/pF}) C_L + 67 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.5 \text{ ns/pF}) C_L + 50 \text{ ns}$	$t_{PLH},$ $t_{PHL}$	5.0 10 15  5.0 10 15  5.0 10 15	— — —  — — —  — — —	175 75 50  175 75 50  350 100 75	350 150 100  350 150 100  450 200 150	ns
Setup Times	$t_{su}$	5.0 10 15	140 50 35	70 25 17	— — —	ns
Hold Times	$t_h$	5.0 10 15	140 50 35	70 25 17	— — —	ns
Clock Pulse Width	$t_{WH}, t_{WL}$	5.0 10 15	330 110 75	165 55 38	— — —	ns
Clock Pulse Frequency	$f_{cl}$	5.0 10 15	— — —	3.0 9.0 13	1.5 4.5 6.5	MHz
Clock Pulse Rise and Fall Time	$t_{TLH}, t_{THL}$	5.0 10 15	— — —	— — —	15 5.0 4.0	$\mu\text{s}$
Removal Times  Set  Reset	$t_{rem}$	5 10 15  5 10 15	90 45 35  50 25 20	10 5 3  -30 -15 -10	— — —  — — —	ns
Set and Reset Pulse Width	$t_{WH}$	5.0 10 15	250 100 70	125 50 35	— — —	ns

7. The formulas given are for the typical characteristics only at  $25^\circ\text{C}$ .

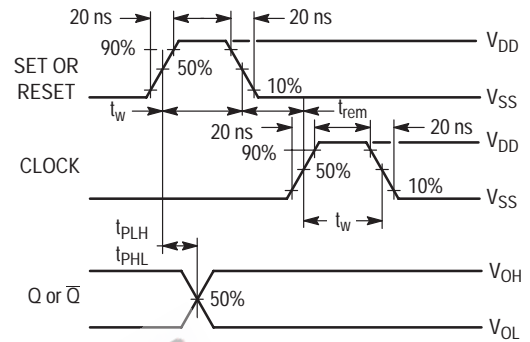
8. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

# MC14027B



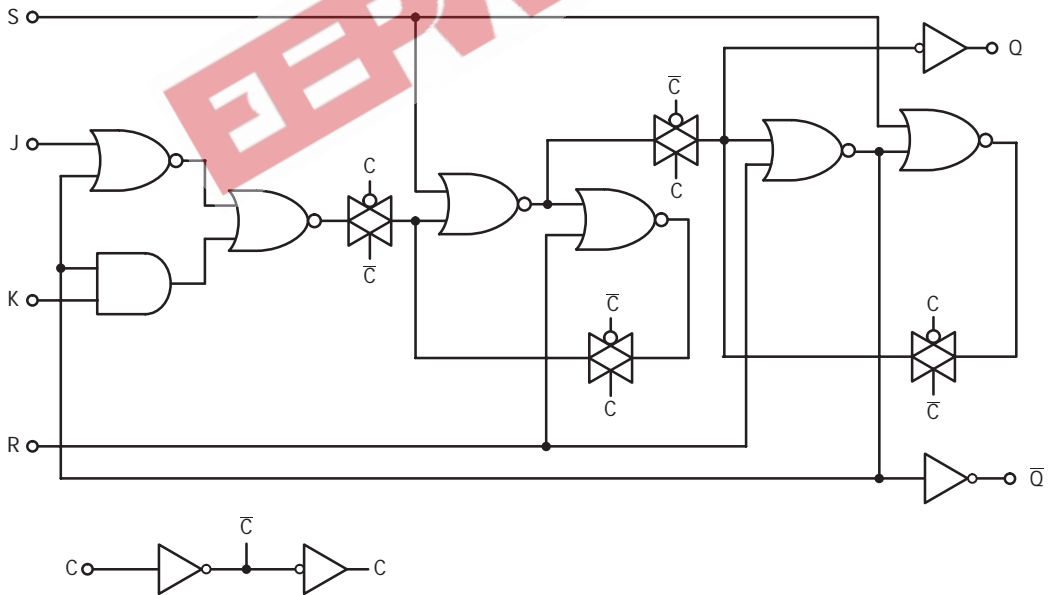
Inputs R and S low.  
For the measurement of  $t_{WH}$ ,  $1/f_{cl}$ , and  $P_D$   
the Inputs J and K are kept high.

**Figure 1. Dynamic Signal Waveforms (J, K, Clock, and Output)**



**Figure 2. Dynamic Signal Waveforms (Set, Reset, Clock, and Output)**

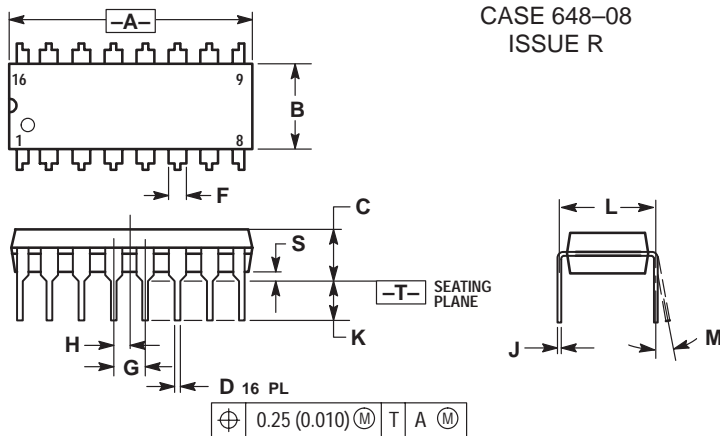
## LOGIC DIAGRAM (1/2 of Device Shown)



# MC14027B

## PACKAGE DIMENSIONS

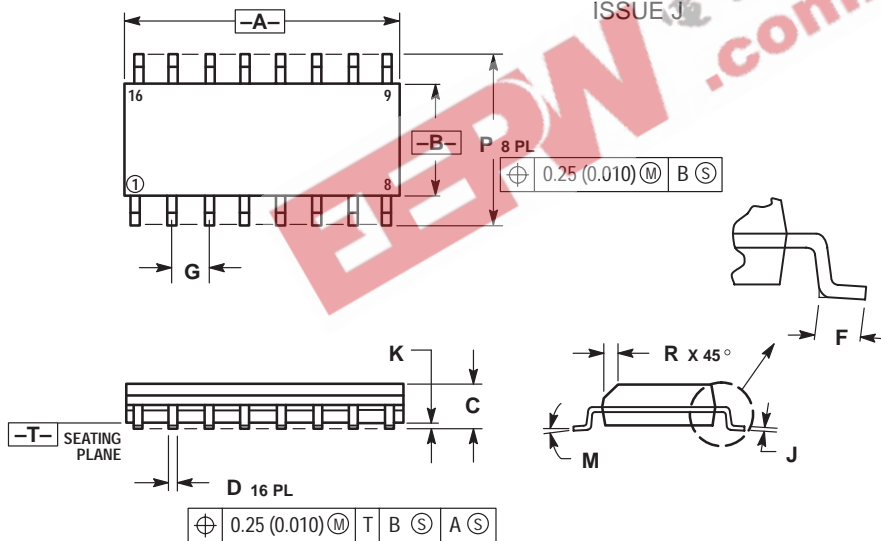
### PDIP-16 P SUFFIX PLASTIC DIP PACKAGE CASE 648-08 ISSUE R



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
  4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
  5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
S	0.020	0.040	0.51	1.01

### SOIC-16 D SUFFIX PLASTIC SOIC PACKAGE CASE 751B-05 ISSUE J



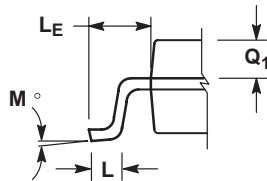
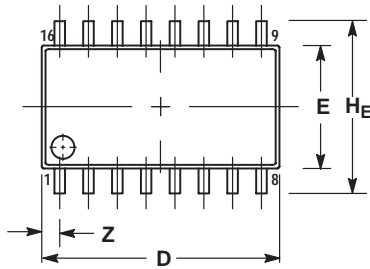
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
  4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
  5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

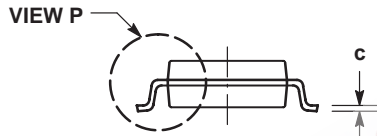
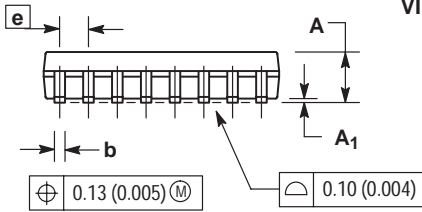
# MC14027B

## PACKAGE DIMENSIONS

SOEIAJ-16  
F SUFFIX  
PLASTIC EIAJ SOIC PACKAGE  
CASE 966-01  
ISSUE O



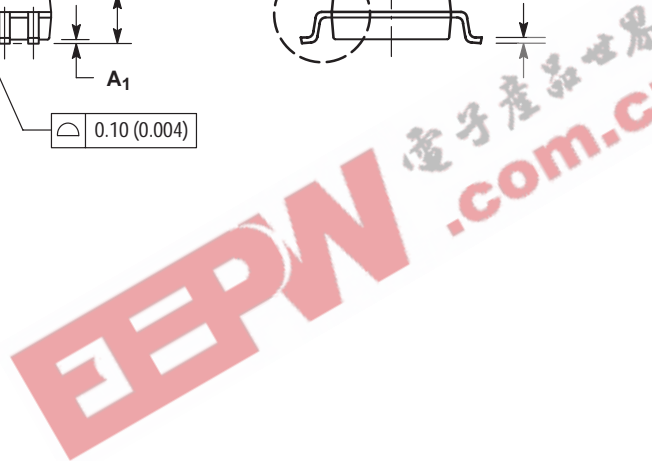
DETAIL P



NOTES:


1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A <sub>1</sub>	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H <sub>E</sub>	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
L <sub>E</sub>	1.10	1.50	0.043	0.059
M	0°	10°	0°	10°
Q <sub>1</sub>	0.70	0.90	0.028	0.035
Z	---	0.78	---	0.031



# MC14027B

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